	REVISIONS		
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
А	Drawing updated to reflect current requirementsrrp	02-07-18	R. Monnin
В	Redrawn. Paragraphs updated to MIL-PRF-38535 requirements drw	14-11-21	Charles F. Saffle
С	Update paragraphs to current MIL-PRF-38535 drw	20-06-10	James R. Eschmeyer

THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.



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REV STATUS	REV		С	С	С	С	С	С	С	С	С	С	С	С	С	
OF SHEETS	SHEET		1	2	3	4	5	6	7	8	9	10	11	12	13	
PMIC N/A	PREPAREI	D BY Rick C.	Office	r		DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990										
STANDARD MICROCIRCUIT	CHECKED	BY harles l	E. Beso	ore		https://www.dla.mil/landandmaritime										
DRAWING	APPROVE	D BY Michael	A. Fry	e		MIC	ROC	CIRCI	UIT, L	INE	AR, C	MOS	S, 8-B	IT, A	/D	
THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS	DRAWING	DRAWING APPROVAL DATE 91-10-02				MICROCIRCUIT, LINEAR, CMOS, 8-BIT, A/D CONVERTER, WITH TRACK/HOLD, MONOLITH SILICON						HIC				
AND AGENCIES OF THE DEPARTMENT OF DEFENSE	REVISION	LEVEL				SI	ZE	CA	GE CC	DE						
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AMSC N/A		5			SHEET 1 OF 13											

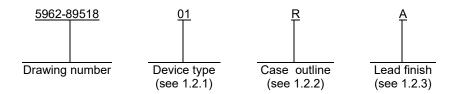
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5962-E339-20

DISTRIBUTION STATEMENT A. Approved for public release. Distribution is unlimited.

## 1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
  - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type</u>. The device type identifies the circuit function as follows:

Device type	Generic number	Circuit function	Total unadjusted error
01	AD7821	CMOS 8-bit ADC with track/hold	±1.0 LSB

1.2.2 <u>Case outlines</u>. The case outlines are as designated in MIL-STD-1835 as follows:

Outline letter	<u>Descriptive designator</u>	<u>Terminals</u>	Package style
R	GDIP1-T20 or CDIP2-T20	20	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings. 1/

Supply voltage to ground (V <sub>SS</sub> )	. 0 V dc to –7.0 V dc
Supply voltage to ground (VDD)	. 0 V dc to +7.0 V dc
Digital input voltage	0.3 V dc to V <sub>DD</sub>
Digital output voltage	0.3 V dc to V <sub>DD</sub>
Positive reference voltage (V <sub>REF+</sub> )	
Negative reference voltage (V <sub>REF-</sub> )	
Input voltage (V <sub>IN</sub> )	
Storage temperature range	65°C to +150°C
Lead temperature (soldering, 10 seconds)	. +300°C
Power dissipation (P <sub>D</sub> )	. 450 mW <u>2</u> /
Thermal resistance, junction-to-case (θ <sub>JC</sub> )	. See MIL-STD-1835
Junction temperature (T <sub>J</sub> )	
• • •	

1.4 Recommended operating conditions.

Supply voltage to ground (V <sub>SS</sub> )	4.75 V dc to -5.25 V dc
Supply voltage to ground (V <sub>DD</sub> )	. +4.75 V dc to +5.25 V dc
Ambient operating temperature range (T <sub>A</sub> )	55°C to +125°C
Positive reference voltage (V <sub>REF+</sub> )	. V <sub>REF-</sub> to V <sub>DD</sub>
Negative reference voltage (V <sub>REF-</sub> )	. Vss to V <sub>REF+</sub>

 $<sup>\</sup>underline{2}$ / Derate above T<sub>A</sub> = +75°C at 6.0 mW/°C.

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<sup>1/</sup> All voltages are with respect to ground.

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

## DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

## DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

## DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at https://quicksearch.dla.mil).

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark.</u> A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

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TA	BLE I. <u>Electrical performance characteristics</u> .
	0

Test	Symbol	Conditions $\underline{1}/, \underline{2}/$ -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
Resolution	Res	This is the minimum resolution for which no missing codes are guaranteed.	1, 2, 3	01	8.0		Bits	
Total unadjusted error	TUE	<u>3</u> /	1, 2, 3	01		±1.0	LSB	
Analog input leakage current	lin		1, 2, 3	01		±3.0	μА	
Reference input resistance	Rin		1, 2, 3	01	1.0	4.0	kΩ	
		CS and RD inputs, V <sub>IH</sub> = 5.25 V, V <sub>IL</sub> = 0 V				±1.0		
Digital input high current	Іін	$\overline{\text{WR}}$ input, V <sub>IH</sub> = 5.25 V, V <sub>IL</sub> = 0 V	1, 2, 3	01		±3.0	μΑ	
		Mode input, $V_{IH} = 5.25 \text{ V}$ , $V_{IL} = 0 \text{ V}$				±200		
Digital input low current	IIL	CS , WR , RD and mode inputs	1, 2, 3	01		-1.0	μА	
Digital output high level voltage	V <sub>OH</sub>	DB <sub>0</sub> -DB <sub>7</sub> , $\overline{\text{OFL}}$ , and $\overline{\text{INT}}$ outputs, $I_{\text{SOURCE}}$ = -360 $\mu\text{A}$	1, 2, 3	01	4.0		V	
Digital output low level voltage	VoL	DB <sub>0</sub> -DB <sub>7</sub> , OFL, and INT outputs, I <sub>SINK</sub> = 1.6 mA	1, 2, 3	01		0.4	V	
Floating state leakage current	Іоит	$DB_0$ - $DB_7$ , $V_{OUT}$ = 5.25 V, then $V_{OUT}$ = 0 V	1, 2, 3	01		±3.0	μΑ	
Supply current from V <sub>DD</sub>	I <sub>DD</sub>	CS = RD = 0 V	1, 2, 3	01		20.0	mA	
Digital input low level	VIL	CS, WR and RD inputs	1,2,3	01		0.8	V	
voltage		Mode input				1.5		
Digital input high level voltage	ViH	CS, WR and RD inputs	1, 2, 3	01	2.4		V	
voltage		Mode input			3.5			
Power supply sensitivity	PSS	$V_{DD}$ = 5.0 V $\pm$ 5%, $V_{REF}$ = 4.75 V maximum	1, 2, 3	01		±0.25	LSB	
Signal to noise ratio	SNR	<u>4</u> /, <u>5</u> /	1, 2, 3	01	45		dB	
Total harmonic distortion	THD	<u>4</u> /, <u>5</u> /	1, 2, 3	01		-50	dB	
Peak harmonic or spurious noise		<u>4</u> /, <u>5</u> /	1, 2, 3	01		-50	dB	
Intermodulation distortion	IMD	Second order terms 5/, 6/	1, 2, 3	01		-50	dB	
intermodulation distortion	IIVID	Third order terms 5/, 6/	1, 2, 0	01		-50	שט	
Supply current from Vss	Iss	CS = RD = 0 V	1, 2, 3	01		100	μΑ	

See footnotes at end of table.

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TABLE I Electrical performance characteristics – co	ntinuad

Test	Symbol	Conditions $\underline{1}$ /, $\underline{2}$ / -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C unless otherwise specified	Group A subgroups	Device type	Lin	nits	Unit
					Min	Max	
Digital input capacitance	CID	CS , WR , RD and mode inputs, See 4.3.1c, T <sub>A</sub> = +25°C	4	01		8.0	pF
Analog input capacitance	CIA	See 4.3.1c	4	01		55	pF
Digital output capacitance	Соит	See 4.3.1c, T <sub>A</sub> = +25°C	4	01		8.0	pF
Slew rate, tracking	SR	<u>4</u> /, <u>5</u> /	7, 8	01		1.6	V/μs
RD pulse width	t <sub>READ1</sub>	Determined by t <sub>ACC1</sub> 7/, 8/	9 10, 11	01	160 240		ns
RD pulse width	t <sub>READ2</sub>	Determined by t <sub>ACC2</sub> 7/, 8/	9 10, 11	01	65 85		ns
CS to RD / WR setup time	tcss	<u>7</u> /, <u>8</u> /	9, 10, 11	01	0		ns
CS to RD / WR hold time	t <sub>CSH</sub>	<u>7</u> /, <u>8</u> /	9, 10, 11	01	0		ns
		$C_L = 50 \text{ pF}, \ 8/$	9	04		70	
CS to RDY delay		pull-up resistor = $4.7 \text{ k}\Omega$	10,11	01		100	ns
Conversion time ( RD mode)	t <sub>CRD</sub>	<u>8</u> /	9	01		700	ns
Conversion time (RD mode)	-010	2	10, 11			975	
Data access time ( $\overline{RD}$ mode)	tacco	<u>8</u> /, <u>9</u> /	9 10, 11	01		750 1050	ns
RD to INT delay (RD mode)	tınth	C <sub>L</sub> = 50 pF <u>8</u> /	9 10, 11	01		80 90	ns
Data hold time	t <sub>DH</sub>	<u>8</u> /, <u>10</u> /	9	01		60 80	ns
Delay time between conversion	t <sub>P</sub>	<u>7</u> /, <u>8</u> /	9	01	350 500		ns
		71.01	9	0.4	0.25	10	
Write pulse width	twR	<u>7</u> /, <u>8</u> /	10, 11	01	0.4	10	μS
Delay time between WR	t <sub>RD</sub>	<u>7</u> /, <u>8</u> /	9	01	250		ns
and RD pulses	יאט	<u>11, 0</u> 1	10, 11	01	450		113
Data access time ( WR / RD	t <sub>ACC1</sub>	<u>8</u> /, <u>9</u> /	9	01		185	ns
mode)			10, 11			275	
RD to INT delay	t <sub>R1</sub>	<u>8</u> /	9 10, 11	01		150 220	ns
WR to INT delay	t <sub>INTL</sub>	$C_L = 50 \text{ pF}$ , see figure 3 $\frac{11}{}$	9 10, 11	01		500 700	ns
Data access time ( WR / RD mode)	t <sub>ACC2</sub>	<u>8</u> /, <u>9</u> /	9	01		90 130	ns
WR to INT delay (stand alone operation)	tihwr	C <sub>L</sub> = 50 pF <u>8</u> /	9	01		80	ns

See footnotes at end of table.

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## TABLE I. Electrical performance characteristics – continued.

Test	Symbol	Conditions $\underline{1}/\underline{2}/$ -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C unless otherwise specified	Group A subgroups	Device type	Lin	nits	Unit
					Min	Max	
Data access time after INT	tıp	<u>8</u> / <u>9</u> /	9	01		45	ns
(stand alone operation)	4D	<u> </u>	10,11	01	·	70	113

- 1/ Unless otherwise specified, V<sub>DD</sub> = +5.0 V; V<sub>REF+</sub> = +5.0 V; V<sub>REF-</sub> = GND = 0 V and V<sub>SS</sub> = 0 V.
- $\underline{2}$ / All input control signals are specified with  $t_R = t_F = 20$  ns (10% to 90% of +5.0 V) and timed from a voltage level of 1.6 V.
- 3/ Includes gain error, offset error and linearity error.
- $4/V_{IN}$  = 99.85 kHz full scale sine wave at 5.0 V peak to peak with f sampling = 500 kHz.
- $5/V_{SS} = -5.0 \text{ V}$ ;  $V_{DD} = +5.0 \text{ V}$ ;  $V_{REF+} = +2.5 \text{ V}$ ;  $V_{REF-} = -2.5 \text{ V}$ .
- 6/ fa (84.72 kHz) and fb (94.97 kHz) combine to produce a full scale sine wave at the analog input with f sampling = 500 kHz.
- 7/ Pass/fail tested only with tested parameter used as a test condition.
- 8/ Refer to timing diagram of figure 3. These parameters are tested to subgroup 9 under group A test requirements.
- 9/ Measured with load circuits of figure 2 and defined as the time required for an output to cross 0.8 V to 2.4 V.
- 10/ Defined as the time required for the data lines to change 0.5 V when loaded with the circuits of figure 2 and is measured only for initial test and after process or design changes which may affect t<sub>DH</sub>.
- 11/ If not tested, shall be guaranteed to the limits specified in table I herein.

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Device type	01
Case outlines	R and 2
Terminal number	Terminal symbol
1	Vin
2	DB <sub>0</sub> (LSB)
3	DB <sub>1</sub>
4	DB <sub>2</sub>
5	DB <sub>3</sub>
6	WR /RDY
7	Mode
8	RD
9	ĪNT
10	GND
11	V <sub>REF</sub> -
12	V <sub>REF+</sub>
13	<del>cs</del>
14	DB <sub>4</sub>
15	DB₅
16	DB <sub>6</sub>
17	DB <sub>7</sub> (MSB)
18	OFL
19	Vss
20	V <sub>DD</sub>

FIGURE 1. <u>Terminal connections</u>.

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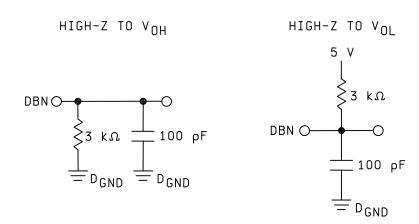
# Pin Function Description

Pin	Symbol	Description
1	Vin	Analog input. Range: V <sub>REF</sub> - ≤ V <sub>IN</sub> ≤ V <sub>REF</sub> +
2	DB <sub>0</sub>	Three-State Data Output (LSB)
3-5	DB <sub>1</sub> - DB <sub>3</sub>	Three-State Data Outputs.
6	WR /RDY	WRITE control input/READY status output.
7	MODE	Mode Selection Input. It determines whether the device operates in the WR-RD or RD mode. This input is internally pulled low through a 50 $\mu$ A current source.
8	RD	READ input. RD must be low to access data from the part.
9	ĪNT	INTERRUPT Output. INT going low indicates that the conversion is complete. INT returns high on the
		rising edge of CS or RD.
10	GND	Ground
11	V <sub>REF</sub> -	Lower limit of reference span.  Range: V <sub>SS</sub> ≤ V <sub>REF-</sub> < V <sub>REF+</sub>
12	V <sub>REF+</sub>	Upper limit of reference span. Range: V <sub>REF-</sub> < V <sub>REF+</sub> ≤ V <sub>DD</sub>
13	CS	Chip Select Input. The device is selected when this input is low.
14-16	DB <sub>4</sub> – DB <sub>6</sub>	Three-State Data Outputs.
17	DB <sub>7</sub>	Three-State Data Output (MSB)
18	OFL	Overflow Output. If the analog input is higher than (V <sub>REF+</sub> - ½ LSB), OFL will be low at the end of conversion. It is a non-three-state output which can be used to cascade 2 or more
		devices to increase resolution.
19	Vss	Negative supply voltage.  Vss = 0 V; Unipolar Operation.  Vss = -5 V; Bipolar Operation.
20	$V_{DD}$	Positive supply voltage, +5 V.

FIGURE 1. <u>Terminal connections</u> - continued.

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## Load circuits for data access time



## Load circuits for data hold time

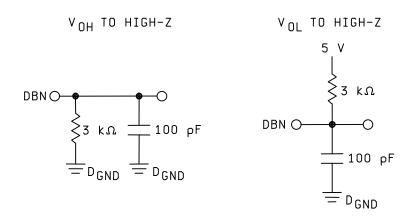
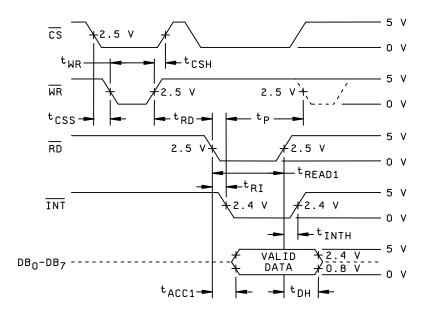


FIGURE 2. Output load circuits.

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# WR-RD mode ( $t_{RD} < t_{INTL}$ )



# WR-RD mode ( $t_{RD} > t_{INTL}$ )

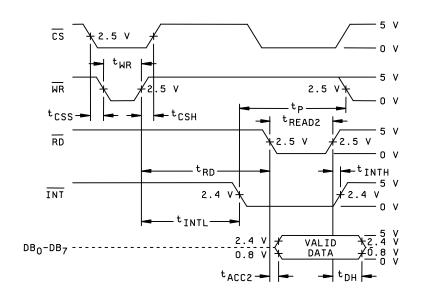
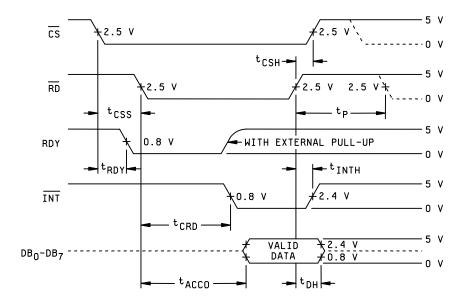


FIGURE 3. Mode timing waveforms.

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## RD mode



WR-RD mode stand-alone operation,  $\overline{CS} = \overline{RD} = 0$ 

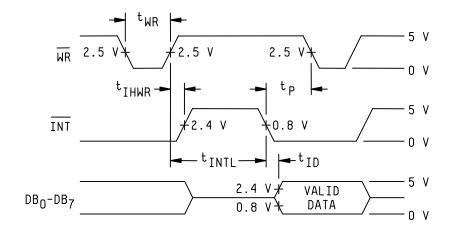


FIGURE 3. <u>Mode timing waveforms</u> – continued.

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- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DLA Land and Maritime -VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DLA Land and Maritime -VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

## 4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1

<sup>\*</sup> PDA applies to subgroup 1.

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<sup>\*\*</sup> Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

## 4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C<sub>IA</sub>, C<sub>ID</sub>, and C<sub>OUT</sub> measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

## 5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform DLA Land and Maritime when a system application requires configuration control and the applicable SMD to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		5962-89518
		REVISION LEVEL C	SHEET 13

## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 20-06-10

Approved sources of supply for SMD 5962-89518 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at: <a href="https://landandmaritimeapps.dla.mil/programs/smcr/">https://landandmaritimeapps.dla.mil/programs/smcr/</a>

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962-8951801RA	24355	AD7821TQ/883B
5962-89518012A	24355	AD7821TE/883B

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGEVendor namenumberand address

24355 Analog Devices

Rt 1 Industrial Park PO Box 9106 Norwood, MA 02062 Point of contact:

> 20 Alpha Chelmsford, MA

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.